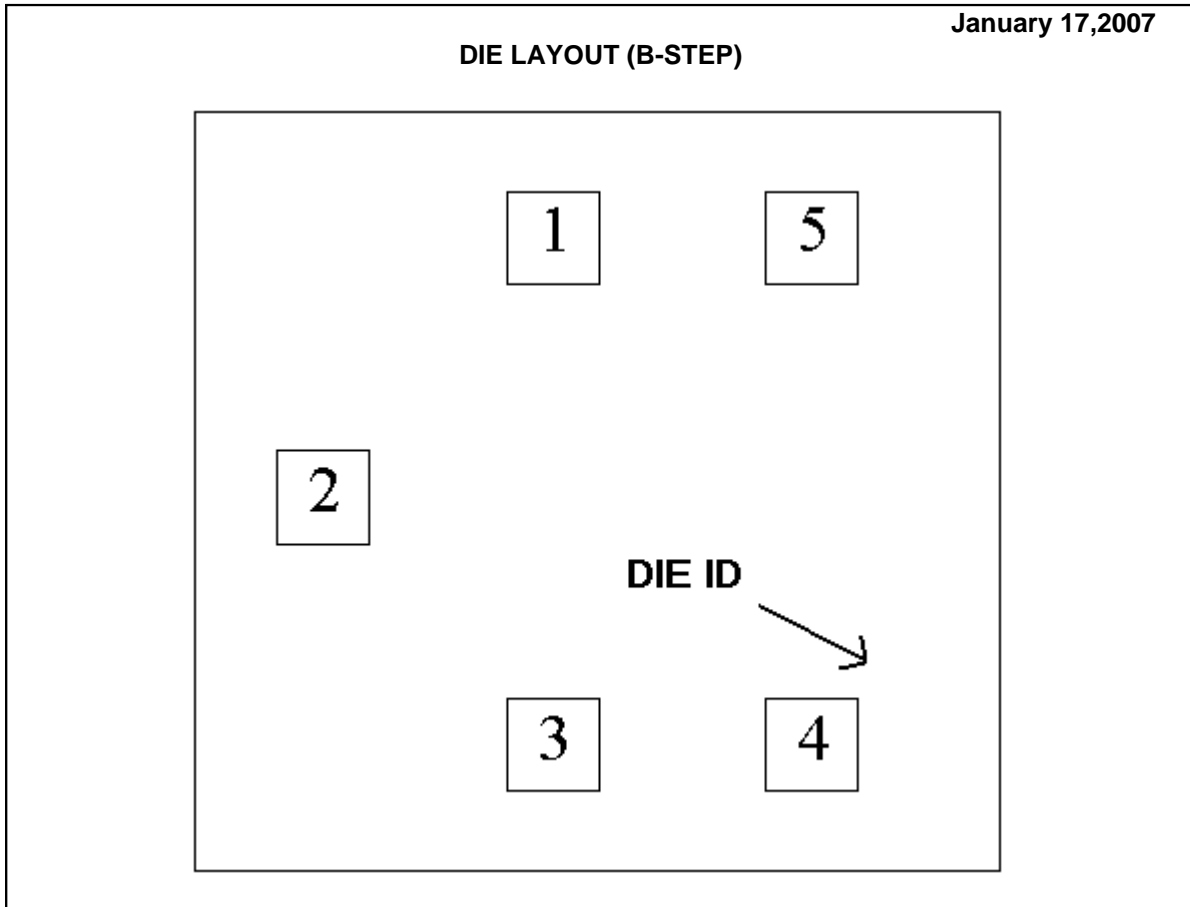


**DS90LV011A MDC MWC
3V LVDS SINGLE HIGH SPEED CMOS DIFFERENTIAL DRIVER**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	DS90LV011AB	Bond Pad Opening Size (min)	102μm x 102μm
Die Step	B	Bond Pad Metalization	Al_ 0.5%Cu
Physical Attributes		Passivation	PECVDOX+NITRIDE
Wafer Diameter	200mm	Back Side Metal	BARE BACK
Die Size (Drawn)	889μm x 838μm 35.0mils x 33.0mils	Back Side Connection	GND
Thickness	254μm Nominal		
Min Pitch	285μm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
VDD	1	-49	280	102	x	102
GND	2	-304	-7	102	x	102
TTL IN	3	-49	-280	102	x	102
OUT +	4	236	-280	102	x	102
OUT -	5	236	280	102	x	102

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